

# GENE-QM87

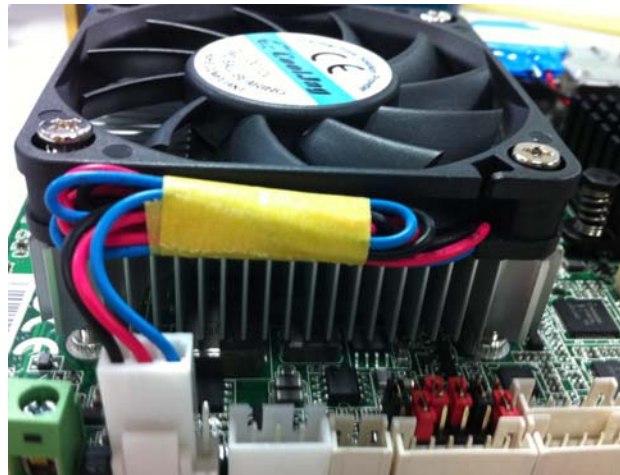
## Thermal Image Analysis Report

Summary	<input checked="" type="checkbox"/> <b>Pass</b> <input type="checkbox"/> <b>Fail</b> <input type="checkbox"/> <b>Pass with Deviation</b> <b>Comment:</b> _____			
<b>Test Result Summary</b>				
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	0
Defect Unsolved	0	0	0	0

Issue date	Approval	Issued by	Test Engineer
2013/06/13	TOM	Rex Chang	Glen Wen

## Sample Configuration & Quantity Under Test

- Model name : GENE-QM87 A0.2
- CPU Board : GENE-QM87 A0.2
- CPU : Intel Core i5-4400E (2.70 GHz)
- Memory : Transcend DDR3L 1600 8GB
- HDD : WD WD5000AAKX 3.5" 500G
- BIOS : GENE-QM87 R0.4 (CQ87AM04)
- Test Software : Windows 7/ Run PassMark Burn In Test 7.0
- Power : AT Power
- CPU Fan



# Thermal Image Analysis

**1. Test Date: 2013-06-12**

**2. Test Product: GENE-QM87**

**3. Test Site: QE Dept.**

**4. Temperature Measurement:**

**4.1. 40 Channel Thermal Recorder:**

**4.1.1 OMRON Inc,**

**4.2.2 Model: ZR-RX40**

**Date of Calibration: 2012/12/11**

**Serial Number: H00452807**

**4.2. IR Scanner: Infrared Camera**

**4.2.1 NEC**

**4.2.2 Model: G100D**

**Date of Calibration: 2013-01-08**

**Serial Number: 1051444**

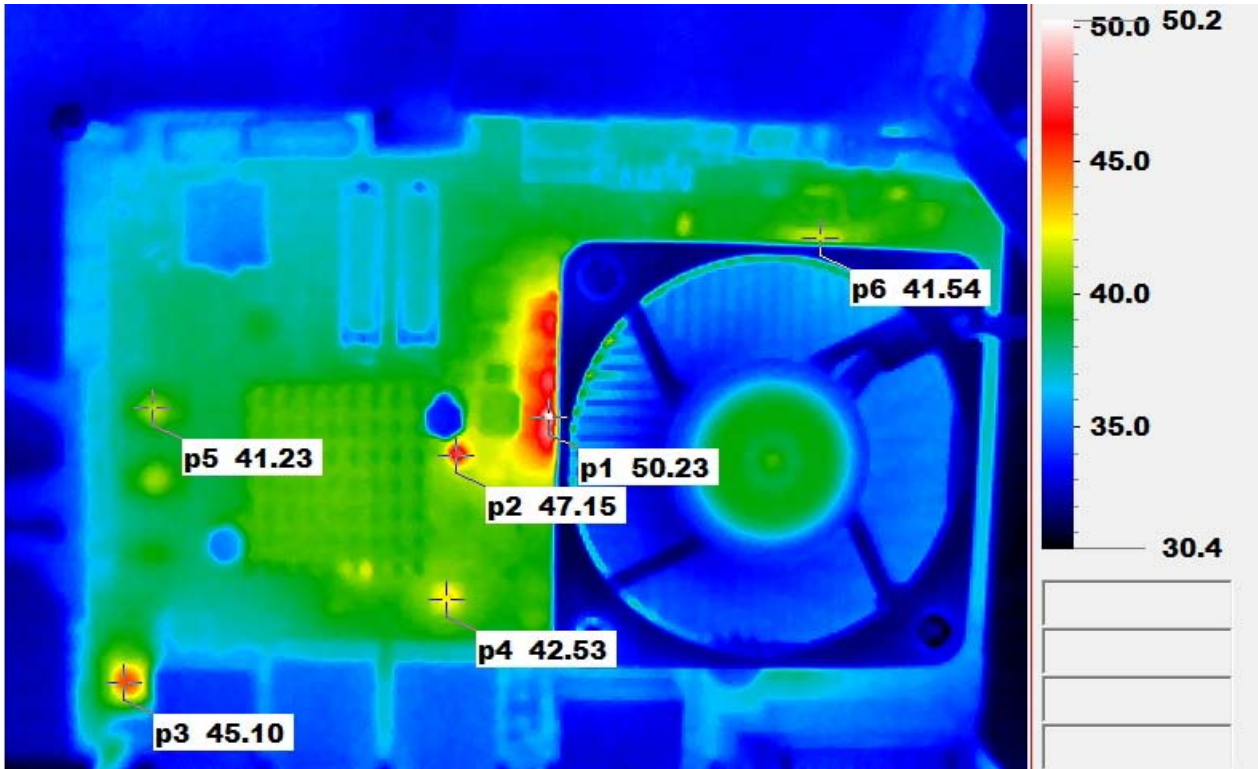
**5. Test Condition:**

**Component Side-1 (Test by ZR-RX40):25.0°C With CPU Fan**

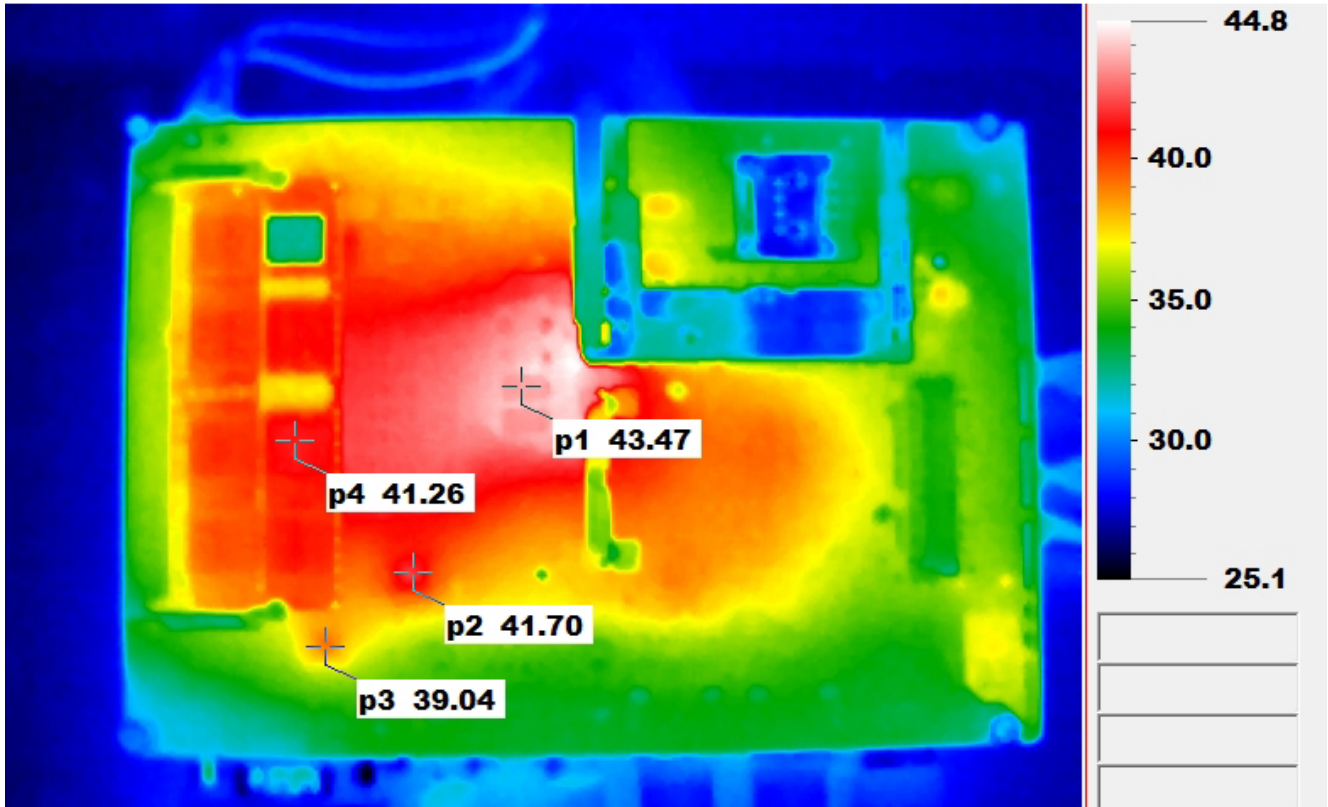
**6. Take Picture Time:**

**After power on 2 hours**

**Temperature Profile Test:**  
**Component Side:**



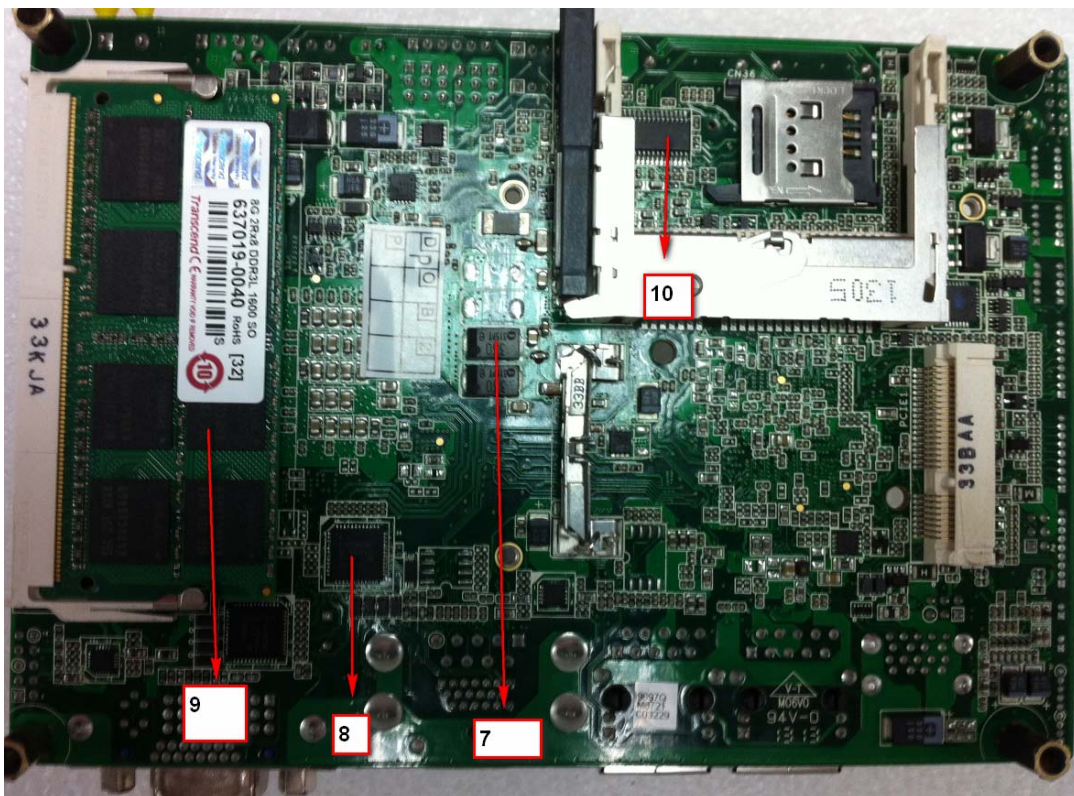
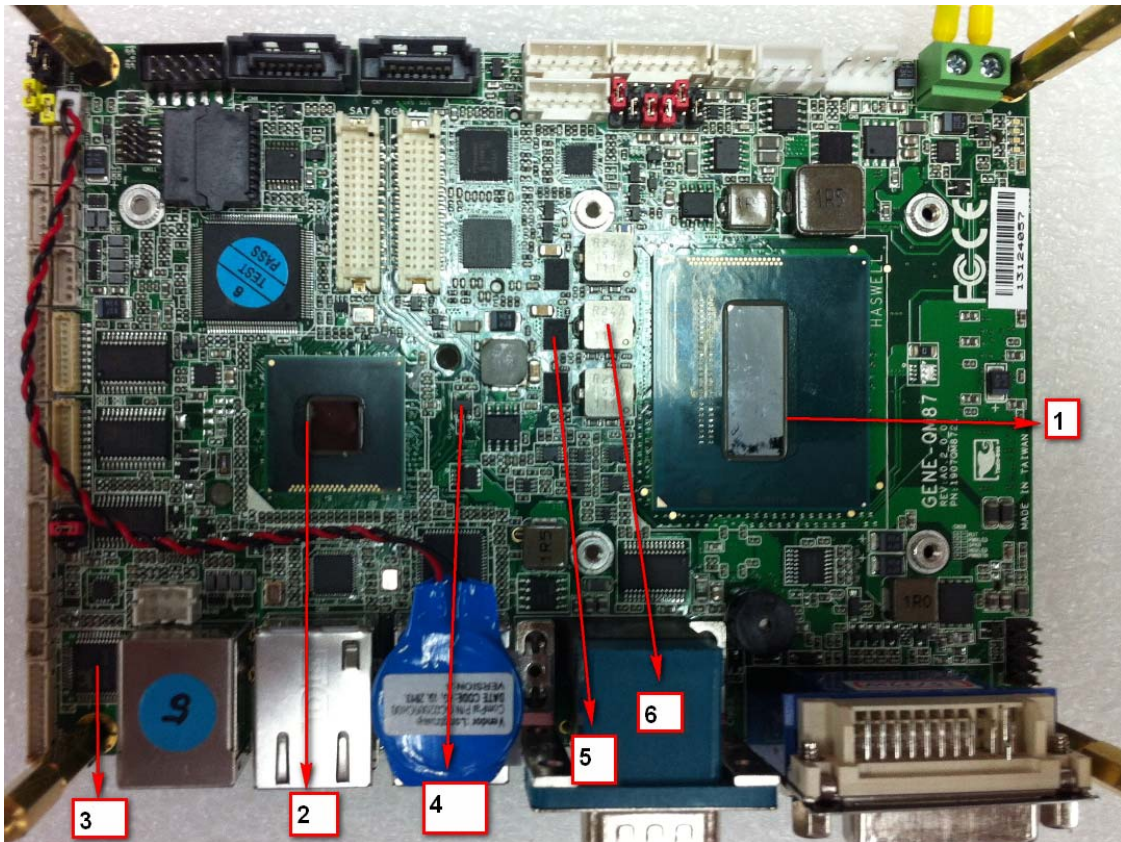
**Back Side:**





### Terminal Recorder:

Measuring Thermal Couple Position :



**Using YOKOGAWA / DARWIN DA100-100-13-1D test**

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25°C	60°C	
1	CPU	Intel Core i5-4400E (2.70 GHz)	105	38.3	73.3	
2	U21	(TF)Chipset PCH.SMD.INTEL.BD82QM87	108	36.3	71.3	
3	U39	(TF)High Definition.Audio Codec.REALTEK.ALC892-GR	100.5	40.1	75.1	
4	U19	(TF)LDO Regulator.500mA.SOT23-5 5P.SMD.UPI.UP0107BMA5-00	100	40.9	75.9	
5	U15	(TF)Synchronous Buck NexFETTM.Power Stage.SMD.TI.CSD97374Q4M	150	36.3	71.3	
6	L4	(TF)COIL.0.24uH.DCR=1mohm.Irms=24Amp.20%.ETQP4LR24AFM	130	35.2	70.2	
7	TC17	(TF)SP CAP.330uF.2.5V.+10/-35%.D2(7.3*4.3*1.9).EEFSX0E331EY	105	38.4	73.4	
8	U57	(TF)for DP to HDMI/DVI.HVQFN 48P.SMD.NXP.PTN3360DBS	100	35.1	70.1	
9	Memory	Transcend DDR3L 1600 8GB	85	39.2	74.2	
10	U41	(TF)IC.Trusted Platform Module.TSSOP28.SMD.Infineon.SLB9635TT1.2	85	33.4	68.4	

**Note(\*):**

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

**3. Judgment Criteria:**

- **Fail** :  $T_m > T_c + 5^{\circ}\text{C}$ ; The measured value is over specification plus margin.
- **Margin** :  $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- **Pass** :  $T_m < T_c - 10^{\circ}\text{C}$ ; The measured value is with safety margin.